

Title (en)

SOLDERABLE CONTACT PIN FOR PRINTED CIRCUIT BOARDS AND PROCESS FOR MANUFACTURING AN ELECTRONIC DEVICE

Title (de)

LÖTBARER KONTAKTPIN FÜR LEITERPLATTEN UND HERSTELLUNGSVERFAHREN FÜR EIN ELEKTRONISCHES BAUELEMENT

Title (fr)

BROCHE DE CONTACT BRASABLE POUR CARTES DE CIRCUIT IMPRIMÉ ET PROCÉDÉ DE FABRICATION D'UN DISPOSITIF ÉLECTRONIQUE

Publication

**EP 2610970 A1 20130703 (EN)**

Application

**EP 12199794 A 20121231**

Priority

IT TO20111245 A 20111230

Abstract (en)

A solderable contact pin for printed circuit boards includes a terminal (2) and a mechanical coupling portion (3), extending along an axis (A). The mechanical coupling portion (3) has a length (L) less than the thickness (T) of a printed circuit board (15) and includes two elastic elements (6, 7), forming a fork along the axis (A) and provided with respective hooking elements (9, 10). The elastic elements (6, 7) are shaped so that, following the insertion of the mechanical coupling portion (3) in an opening with a width (W) less than a maximum distance (D) between respective outer edges (6a, 7a) of the elastic elements (6, 7), respective free ends (6b, 7b) of the elastic elements (6, 7) are rotated towards each other and the hooking elements (9, 10) are turned outwards to prevent the extraction of the mechanical coupling portion (3) from the opening.

IPC 8 full level

**H01R 12/58** (2011.01)

CPC (source: EP)

**H01R 12/585** (2013.01)

Citation (search report)

- [I] DE 4132996 A1 19921119 - TELEFUNKEN SYSTEMTECHNIK [DE]
- [I] DE 4321065 A1 19950119 - PHOENIX CONTACT GMBH & CO [DE]
- [I] US 3428934 A 19690218 - REIDER GEORGE SYLVESTER JR, et al
- [I] GB 2121620 A 19831221 - OXLEY DEV CO LTD
- [A] US 2004154907 A1 20040812 - BLOSSFELD MIKE [US], et al

Cited by

CN105938947A

Designated contracting state (EPC)

AL AT BE BG CH CY CZ DE DK EE ES FI FR GB GR HR HU IE IS IT LI LT LU LV MC MK MT NL NO PL PT RO RS SE SI SK SM TR

Designated extension state (EPC)

BA ME

DOCDB simple family (publication)

**EP 2610970 A1 20130703; EP 2610970 B1 20180725**; ES 2682245 T3 20180919; IT TO20111245 A1 20130701; PL 2610970 T3 20181231; PT 2610970 T 20181010

DOCDB simple family (application)

**EP 12199794 A 20121231**; ES 12199794 T 20121231; IT TO20111245 A 20111230; PL 12199794 T 20121231; PT 12199794 T 20121231